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**SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE
SAME**

Appl. No. : 10/710,399
Applicant : Min-Jer Lin
Filed : July 8, 2004
TC/A.U. : 2818
Examiner : DAO H. NGUYEN
Docket No. : LKSP0027USA0
Customer No. : 27765

Confirmation No. 4398

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

Do Not Enter
Thanks,
DN
10/05/2006

AMENDMENT

5 Sir:

In response to the Office action of June 9, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of
10 this paper.

Remarks/Arguments begin on page 7 of this paper.